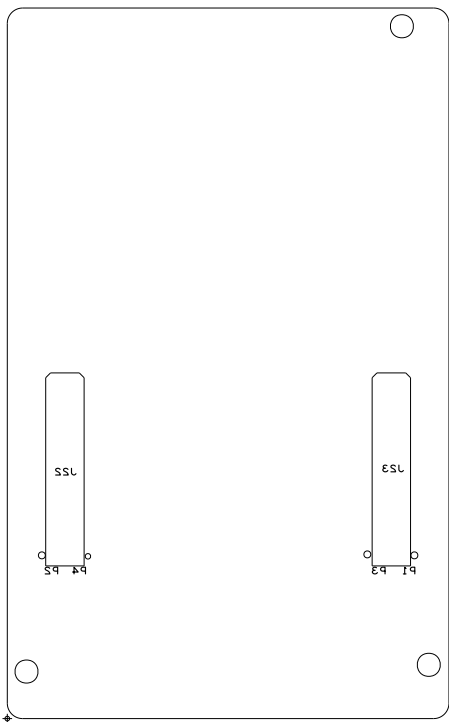


COMPANY NAME : TEXAS INSTRUMENTS
DATE: JUNE 24 2014
PART NO/CARD REF: CC3200LP 3.2
FILM LAYER: ASSEMBLY PRIMARY SIDE



COMPANY NAME : TEXAS INSTRUMENTS
DATE: JUNE 24 2014
PART NO/CARD REF: CC3200LP 3.2
FILM LAYER: ASSEMBLY SECONDARY SIDE

8 7 6 1

D

D

C

C

B

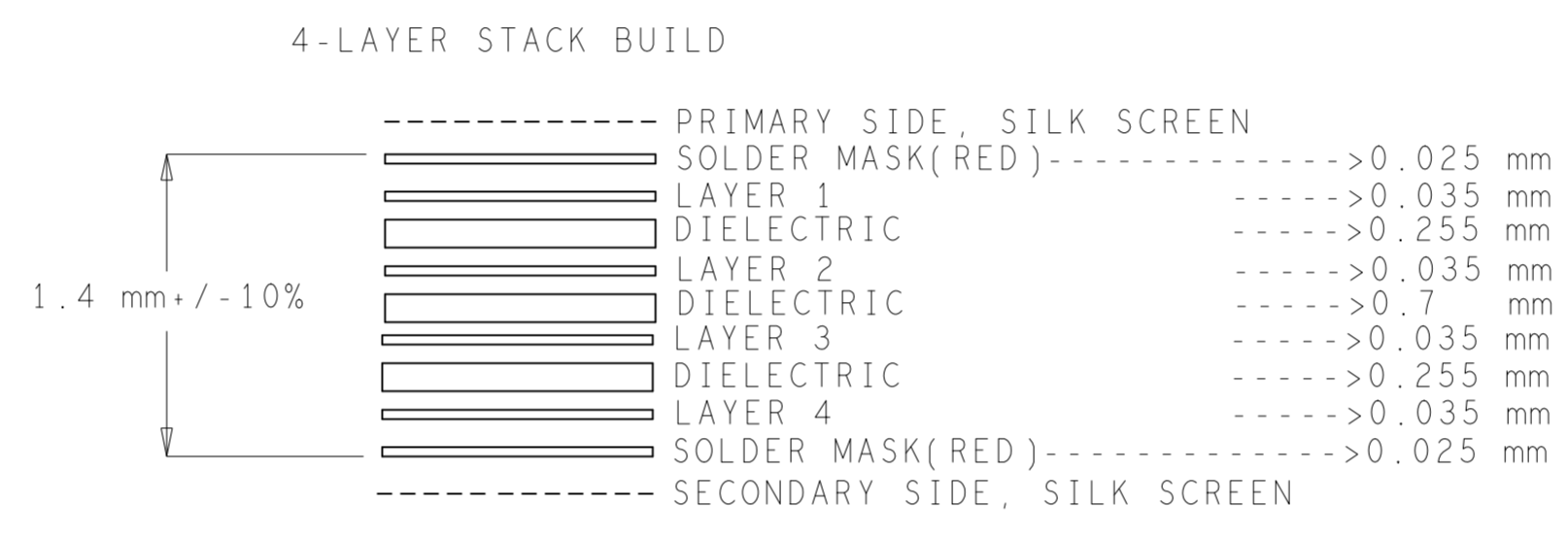
B

A

A

CONTROLLED IMPEDANCE USING CPW with GND

LAYER NO	CONDUCTOR WIDTH	SPACING	IMPEDANCE +/- 10%	REFERENCE GND
1	18.0 MIL	15 mil	50 OHMS	L2

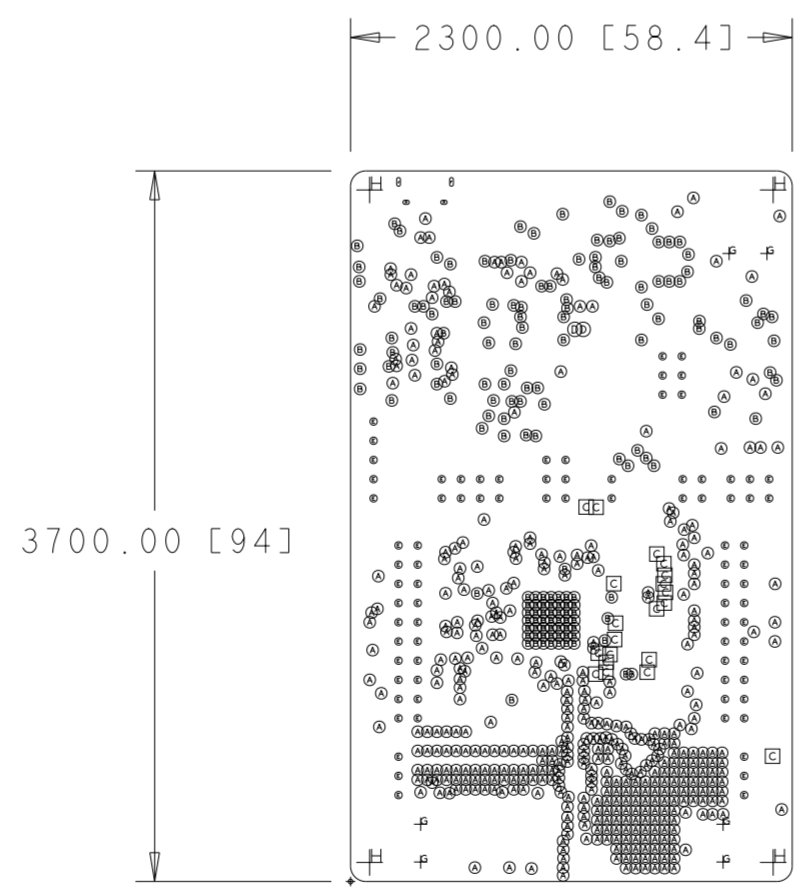


SECTION A-A

NO SCALE

GENERAL NOTES-- UNLESS OTHERWISE SPECIFIED:

- 1 FABRICATE PER IPC-6012A CLASS 2
- 2 SURFACE FINISH : ENIG
- 3 MATERIAL : FR4
- 5 COPPER WT: 1 Oz
- 6 SOLDER MASK CLEARANCE IS GIVEN SAME AS PAD SIZE EXCEPT FIDUCIAL VENDOR SHALL MODIFY THE MASK CLEARANCE AS PER THE REQUIRED MANUFACTURING TOLERANCE
- 7 SOLDER MASK COLOUR : RED



DRILL CHART: TOP to BOTTOM  
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
⊙	8.0	+3.0/-3.0	PLATED	433
*	12.0	+3.0/-3.0	PLATED	158
⊠	16.0	+3.0/-3.0	PLATED	20
⊙	20.0	+3.0/-3.0	PLATED	2
*	38.0	+3.0/-3.0	PLATED	83
#	39.3701	+3.0/-3.0	PLATED	6
#	98.4252	+2.0/-2.0	NON-PLATED	4
*	33.4646x21.6535	+3.0/-3.0	PLATED	2
*	45.2756x19.685	+3.0/-3.0	PLATED	2

COMPANY NAME : TEXAS INSTRUMENTS
DATE: JUNE 24 2014
PART NO/CARD REF: CC3200LP 3.2
FILM LAYER: FABRICATION DRAWING

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS	TEXAS INSTRUMENTS	
	FABRICATION DRAWING CC3200LP 3.2	
DATE JUNE 24 2014	PART NUMBER: CC3200LP 3.2	REV C

8 7 6 5 4 3 2 1 CAD DATA DO NOT MANUALLY UPDATE

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